PCU9655

16-channel UFm 5 MHz bus 100 mA 40 V LED driver

Rev. 2 — 2 October 2012 Product data sheet

1. General description

The PCU9655 is a UFm I^2C-bus controlled 16-channel LED driver optimized for voltage switch dimming and blinking 100 mA Red/Green/Blue/Amber (RGBA) LEDs. Each LED output has its own 8-bit resolution (256 steps) fixed frequency individual PWM controller that operates at approximately 31.25 kHz with a duty cycle that is adjustable from 0 % to 99.6 % to allow the LED to be set to a specific brightness value. An additional 8-bit resolution (256 steps) group PWM controller has both a fixed frequency of about 122 Hz and an adjustable frequency roughly between 15 Hz to once every 16.8 seconds with a duty cycle that is adjustable from 0 % to 99.6 % that is used to either dim or blink all LEDs with the same value.

Each LED output can be off, on (no PWM control), set at its individual PWM controller value or at both individual and group PWM controller values. The PCU9655 operates with a supply voltage range of 3 V to 5.5 V and the 100 mA open-drain outputs allow voltages up to 40 V.

The PCU9655 is one of the first LED controller devices in a new Ultra Fast mode (UFm) family. UFm devices offer higher frequency (up to 5 MHz).

Software programmable LED Group and three Sub Call I^2C-bus addresses allow all or defined groups of PCU9655 devices to respond to a common I^2C-bus address, allowing for example, all red LEDs to be turned on or off at the same time, thus minimizing I^2C-bus commands. On power-up, PCU9655 will have a unique Sub Call address to identify it as a 16-channel LED driver. This allows mixing of devices with different channel widths. Five hardware address pins on PCU9655 allow up to 32 devices on the same bus.

The Software Reset (SWRST) function allows the master to perform a reset of the PCU9655 through the I^2C-bus, identical to the Power-On Reset (POR) that initializes the registers to their default state causing the output voltage switches to be OFF (LED off). This allows an easy and quick way to reconfigure all device registers to the same condition.

Additionally, a thermal shutdown feature protects the device when the internal junction temperature exceeds the overtemperature threshold.

2. Features and benefits

- 16 LED drivers. Each output programmable at:
  - Off
  - On
  - Programmable LED brightness
  - Programmable group dimming/blinking mixed with individual LED brightness
  - Programmable LED output enable delay to reduce EMI and surge currents
- 16 output channels can sink up to 100 mA, tolerate up to 40 V when OFF
- 5 MHz Ultra Fast-mode unidirectional interface (write only)
- 256-step (8-bit) linear programmable brightness per LED output varying from fully off (default) to maximum brightness using a 31.25 kHz PWM signal
- 256-step group brightness control allows general dimming (using a 122 Hz PWM signal) from fully off to maximum brightness (default)
- 256-step group blinking with frequency programmable from 15 Hz to 16.8 s and duty cycle from 0 % to 99.6 %
- Output state change programmable on the Acknowledge (this ninth bit is always set to 1 by UFm I^2C-bus master) or the STOP Command to update outputs byte-by-byte or all at the same time (default to 'Change on STOP').
- Five hardware address pins allow 32 PCU9655 devices to be connected to the same UFM bus and to be individually programmed
- Four software programmable I^2C-bus addresses (one LED Group Call address and three LED Sub Call addresses) allow groups of devices to be addressed at the same time in any combination (for example, one register used for 'All Call' so that all the PCU9655s on the UFm bus can be addressed at the same time and the second register used for three different addresses so that $1/3$ of all devices on the bus can be addressed at the same time in a group). Software enable and disable for each programmable UFm bus address.
- Unique power-up default Sub Call address allows mixing of devices with different channel widths
- Software Reset feature (SWRST Call) allows the device to be reset through the UFm bus
- 8 MHz internal oscillator requires no external components
- Internal power-on reset
- Noise filter on USDA/USCL inputs
- Glitch free LED outputs on power-up
- Thermal shutdown with thermal protection
- Operating power supply voltage (V_{DD}) range of 3 V to 5.5 V
- 5.5 V tolerant inputs on non-LED pins
- −40 °C to +85 °C operation
- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 Class II, Level B
- Packages offered: TSSOP28

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3. Applications

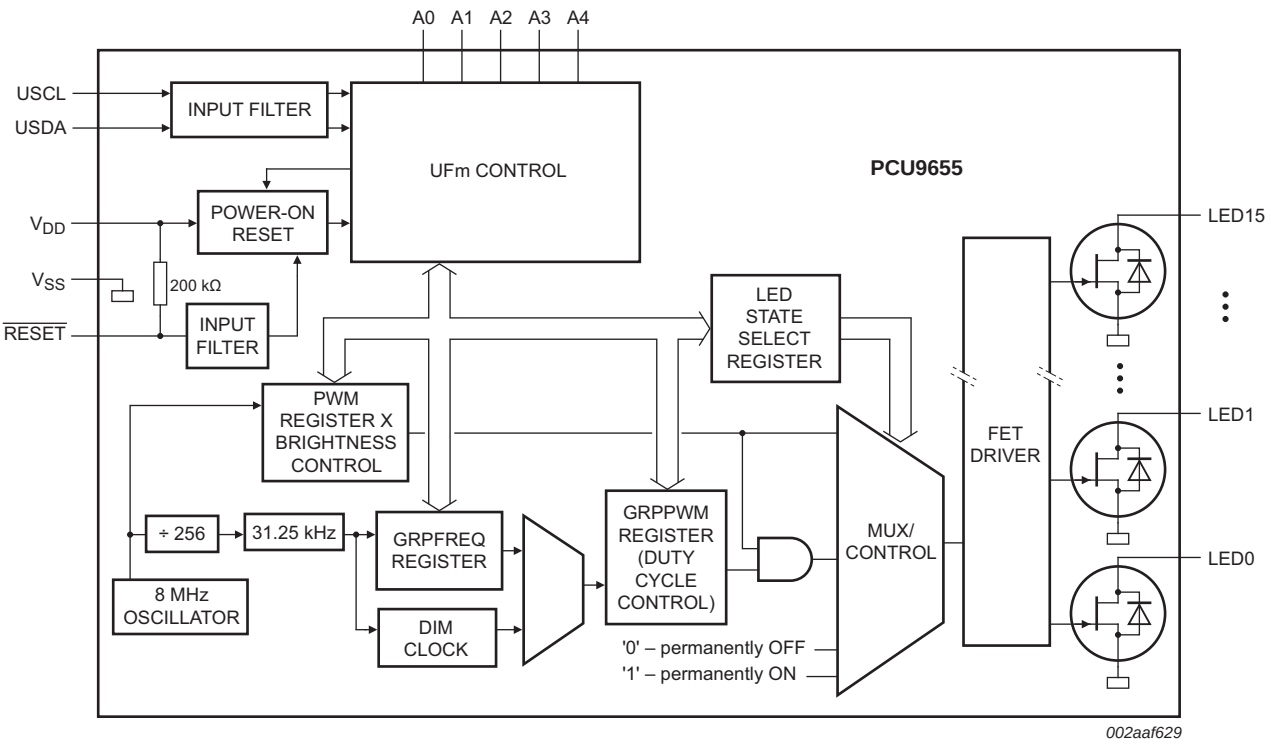
- Amusement products
- RGB or RGBA LED drivers
- LED status information
- LED displays
- LCD backlights
- Keypad backlights for cellular phones or handheld devices

4. Ordering information

Table 1. Ordering information

Type number	Topside mark	Package		
		Name	Description	Version
PCU9655PW	PCU9655	TSSOP28	plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
PCU9655PW1	PU96551	TSSOP28	plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1

5. Block diagram



Dim repetition rate = 122 Hz.

Blink repetition rate = 15 Hz to every 16.8 seconds.

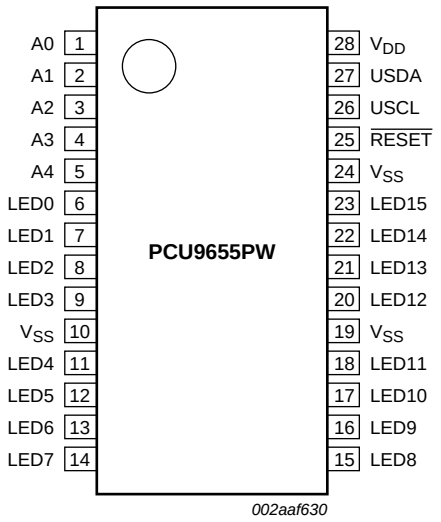
Fig 1. Block diagram of PCU9655PW

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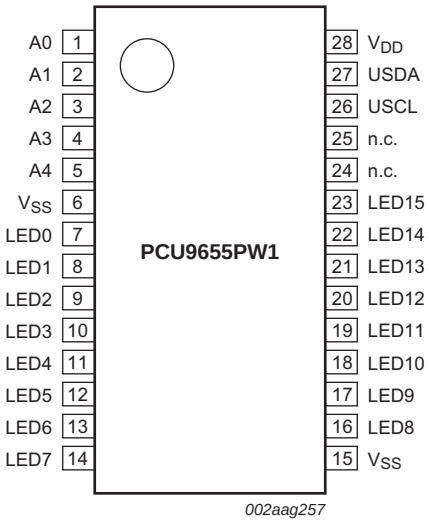
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6. Pinning information

6.1 Pinning



a. PCU9655PW



b. PCU9655PW1

Fig 2. Pin configuration for TSSOP28

6.2 Pin description

Table 2. Pin description

Symbol	Pin		Type	Description
	PCU9655PW	PCU9655PW1		
A0	1	1	I	address input 0[1]
A1	2	2	I	address input 1[1]
A2	3	3	I	address input 2[1]
A3	4	4	I	address input 3[1]
A4	5	5	I	address input 4[1]
LED0	6	7	O	LED driver 0
LED1	7	8	O	LED driver 1
LED2	8	9	O	LED driver 2
LED3	9	10	O	LED driver 3
V_{SS}	10, 19, 24	6, 15	ground	supply ground
LED4	11	11	O	LED driver 4
LED5	12	12	O	LED driver 5
LED6	13	13	O	LED driver 6
LED7	14	14	O	LED driver 7
LED8	15	16	O	LED driver 8
LED9	16	17	O	LED driver 9
LED10	17	18	O	LED driver 10

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Table 2. Pin description *...continued*

Symbol	Pin		Type	Description
	PCU9655PW	PCU9655PW1		
LED11	18	19	O	LED driver 11
LED12	20	20	O	LED driver 12
LED13	21	21	O	LED driver 13
LED14	22	22	O	LED driver 14
LED15	23	23	O	LED driver 15
$\overline{\text{RESET}}$	25	-	I	active LOW reset input
n.c.	-	24, 25	-	do not connect; reserved input
USCL	26	26	I	UFm serial clock line
USDA	27	27	I	UFm serial data line
V_{DD}	28	28	power supply	supply voltage

[1] In order to obtain the best system level ESD performance, a standard pull-up resistor (10 kΩ typical) is required for any address pin connecting to V_{DD}. For additional information on system level ESD performance, please refer to application notes AN10897 and AN11131.

7. Functional description

Refer to Figure 1 “Block diagram of PCU9655PW”.

7.1 Device addresses

Following a START condition, the bus master must output the address of the slave it is accessing.

For PCU9655 there are a maximum of 32 possible programmable addresses using the five hardware address pins A[4:0].

7.1.1 Regular UFm I²C-bus slave address

The I²C-bus slave address of the PCU9655 is shown in Figure 3. To conserve power, no internal pull-up resistors are incorporated on the hardware selectable address pins and they must be pulled HIGH or LOW externally.

Remark: Reserved I²C-bus addresses must be used with caution since they can interfere with:

- ‘reserved for future use’ I²C-bus addresses (0000 011, 1111 1XX)
- slave devices that use the 10-bit addressing scheme (1111 0XX)
- slave devices that are designed to respond to the General Call address (0000 000)
- High-speed mode (Hs-mode) master code (0000 1XX)

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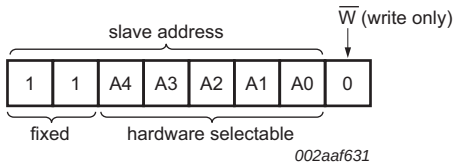


Fig 3. PCU9655 slave address

The last bit of the address byte defines the operation to be performed. Only writes to PCU9655 are supported, therefore the last bit is set to 0.

7.1.2 LED All Call UFm I²C-bus address

- Default power-up value (ALLCALLADR register): A0h or 1010 000X
- Programmable through I²C-bus (volatile programming)
- At power-up, LED All Call I²C-bus address is enabled

See Section 7.3.9 “ALLCALLADR, LED All Call I²C-bus address” for more detail.

Remark: The default LED All Call I²C-bus address (A0h or 1010 000X) must not be used as a regular I²C-bus slave address since this address is enabled at power-up. All of the PCU9655s on the UFm I²C-bus will respond to the address if sent by the I²C-bus master.

7.1.3 LED Sub Call UFm I²C-bus addresses

- 3 different I²C-bus addresses can be used
- Default power-up values:
  - SUBADR1 register: ACh or 1010 110X
  - SUBADR2 register: ACh or 1010 110X
  - SUBADR3 register: ACh or 1010 110X
- Programmable through UFm I²C-bus (volatile programming)
- At power-up, SUBADR1 is enabled while SUBADR2 and SUBADR3 I²C-bus addresses are disabled.

Remark: At power-up SUBADR1 identifies this device as a 16-channel driver.

See Section 7.3.8 “SUBADR[3:1] LED Sub Call UFm I²C-bus addresses for PCU9655” for more detail.

Remark: The default LED Sub Call I²C-bus addresses may be used as regular I²C-bus slave addresses as long as they are disabled in bit [3:1] = 000 of MODE1 register.

7.2 Control register

Following slave address, LED All Call address or LED Sub Call address, the bus master will send a byte to the PCU9655, which will be stored in the Control register.

The lowest 7 bits are used as a pointer to determine which register will be accessed (D[6:0]). The highest bit is used as Auto-Increment Flag (AIF). The AIF is active by default at power-up.

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This AIF bit along with the MODE1 register bit 5 and bit 6 provide the Auto-Increment feature.



reset state = 80h

Remark: The Control register does not apply to the Software Reset I²C-bus address.

Fig 4. Control register

When the Auto-Increment Flag is set (AIF = 1), the seven low-order bits of the Control register are automatically incremented after a write. This allows the user to program the registers sequentially. Four different types of Auto-Increment are possible, depending on AI1 and AI0 values of MODE1 register.

Table 3. Auto-Increment options

AIF	AI1[1]	AI0[1]	Function
0	0	0	no Auto-Increment
1	0	0	Auto-Increment for registers (00h to 41h). D[6:0] roll over to 00h after register 41h is accessed.
1	0	1	Auto-Increment for individual brightness registers only (0Ah to 19h). D[6:0] roll over to 0Ah after the last register (19h) is accessed.
1	1	0	Auto-Increment for MODE1 to PWM15 control registers (00h to 19h). D[6:0] roll over to 00h after the last register (19h) is accessed.
1	1	1	Auto-Increment for global control registers and individual brightness registers (08h to 19h). D[6:0] roll over to 08h after the last register (19h) is accessed.

[1] AI1 and AI0 come from MODE1 register.

Remark: Other combinations not shown in Table 3 (AIF + AI[1:0] = 001b, 010b and 011b) are reserved and must not be used for proper device operation.

AIF + AI[1:0] = 000b is used when the same register must be accessed several times during a single I²C-bus communication, for example, changes the brightness of a single LED. Data is overwritten each time the register is accessed during a write operation.

AIF + AI[1:0] = 100b is used when all the registers, except 42h PWMALL register, must be sequentially accessed, for example, power-up programming.

AIF + AI[1:0] = 101b is used when the 16 LED drivers must be individually programmed with different values during the same I²C-bus communication, for example, changing color setting to another color setting.

AIF + AI[1:0] = 110b is used when MODE1 to PWM15 registers must be programmed with different settings during the same I²C-bus communication.

AIF + AI[1:0] = 111b is used when the 16 LED drivers must be individually programmed with different values in addition to global programming.

Only the 7 least significant bits D[6:0] are affected by the AIF, AI1 and AI0 bits.

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When the Control register is written, the register entry point determined by D[6:0] is the first register that will be addressed (write operation), and can be anywhere between 00h and 41h (as defined in Table 4). When AIF = 1, the Auto-Increment Flag is set and the rollover value at which the register increment stops and goes to the next one is determined by AIF, AI1 and AI0. See Table 3 for rollover values. For example, if MODE1 register bit AI1 = 0 and AI0 = 1 and if the Control register = 1001 0000, then the register addressing sequence will be (in hexadecimal):
10 → 11 → … → 19 → 0A → 0B → … → 19 → 0A → 0B → … as long as the master keeps writing data.

If MODE1 register bit AI1 = 0 and AI0 = 0 and if the Control register = 1010 0010, then the register addressing sequence will be (in hexadecimal):
22 → 23 → … → 41 → 00 → 01 → … → 19 → 0A → 0B → … as long as the master keeps writing data.

If MODE1 register bit AI1 = 0 and AI0 = 1 and if the Control register = 1000 0101, then the register addressing sequence will be (in hexadecimal):
05 → 06 → … → 19 → 0A → 0B → … → 19 → 0A → 0B → … as long as the master keeps writing data.

7.3 Register definitions

Table 4. Register summary[1]

Register number (hexadecimal)	D6	D5	D4	D3	D2	D1	D0	Name	Type	Function
00h	0	0	0	0	0	0	0	MODE1	write only	Mode register 1
01h	0	0	0	0	0	0	1	MODE2	write only	Mode register 2
02h	0	0	0	0	0	1	0	LEDOUT0	write only	LED output state 0
03h	0	0	0	0	0	1	1	LEDOUT1	write only	LED output state 1
04h	0	0	0	0	1	0	0	LEDOUT2	write only	LED output state 2
05h	0	0	0	0	1	0	1	LEDOUT3	write only	LED output state 3
06h	0	0	0	0	1	1	0	-	write only	not used[1]
07h	0	0	0	0	1	1	1	-	write only	not used[1]
08h	0	0	0	1	0	0	0	GRPPWM	write only	group duty cycle control
09h	0	0	0	1	0	0	1	GRPFREQ	write only	group frequency
0Ah	0	0	0	1	0	1	0	PWM0	write only	brightness control LED0
0Bh	0	0	0	1	0	1	1	PWM1	write only	brightness control LED1
0Ch	0	0	0	1	1	0	0	PWM2	write only	brightness control LED2
0Dh	0	0	0	1	1	0	1	PWM3	write only	brightness control LED3
0Eh	0	0	0	1	1	1	0	PWM4	write only	brightness control LED4
0Fh	0	0	0	1	1	1	1	PWM5	write only	brightness control LED5
10h	0	0	1	0	0	0	0	PWM6	write only	brightness control LED6
11h	0	0	1	0	0	0	1	PWM7	write only	brightness control LED7
12h	0	0	1	0	0	1	0	PWM8	write only	brightness control LED8
13h	0	0	1	0	0	1	1	PWM9	write only	brightness control LED9
14h	0	0	1	0	1	0	0	PWM10	write only	brightness control LED10

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Table 4. Register summary[1] *…continued*

Register number (hexadecimal)	D6	D5	D4	D3	D2	D1	D0	Name	Type	Function
15h	0	0	1	0	1	0	1	PWM11	write only	brightness control LED11
16h	0	0	1	0	1	1	0	PWM12	write only	brightness control LED12
17h	0	0	1	0	1	1	1	PWM13	write only	brightness control LED13
18h	0	0	1	1	0	0	0	PWM14	write only	brightness control LED14
19h	0	0	1	1	0	0	1	PWM15	write only	brightness control LED15
1Ah to 39h	-	-	-	-	-	-	-	-	write only	not used[1]
3Ah	0	1	1	1	0	1	0	OFFSET	write only	Offset/delay on LEDn outputs
3Bh	0	1	1	1	0	1	1	SUBADR1	write only	I^2C-bus subaddress 1
3Ch	0	1	1	1	1	0	0	SUBADR2	write only	I^2C-bus subaddress 2
3Dh	0	1	1	1	1	0	1	SUBADR3	write only	I^2C-bus subaddress 3
3Eh	0	1	1	1	1	1	0	ALLCALLADR	write only	All Call I^2C-bus address
3Fh	0	1	1	1	1	1	1	RESERVED1	write only	reserved[2]
40h	1	0	0	0	0	0	0	RESERVED2	write only	reserved[2]
41h	1	0	0	0	0	0	1	RESERVED3	write only	reserved[2]
42h	1	0	0	0	0	1	0	PWMALL	write only	brightness control for all LEDn
43h to 7Fh	-	-	-	-	-	-	-	-	write only	not used[1]

[1] **Remark:** Writing to registers marked ‘not used’ will be ignored.

[2] **Remark:** Writing to registers marked ‘reserved’ will not change any functionality in the chip.

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7.3.1 MODE1 — Mode register 1

Table 5. MODE1 - Mode register 1 (address 00h) bit description

*Legend: * default value.*

Bit	Symbol	Access	Value	Description
7	AIF	-	-	not used
6	AI1	W only	0*	Auto-Increment bit 1 = 0. Auto-increment range as defined in Table 3.
			1	Auto-Increment bit 1 = 1. Auto-increment range as defined in Table 3.
5	AI0	W only	0*	Auto-Increment bit 0 = 0. Auto-increment range as defined in Table 3.
			1	Auto-Increment bit 0 = 1. Auto-increment range as defined in Table 3.
4	SLEEP	W only	0*	Normal mode[1].
			1	Low power mode. Oscillator off[2].
3	SUB1	W only	0	PCU9655 does not respond to I^2C-bus subaddress 1.
			1*	PCU9655 responds to I^2C-bus subaddress 1.
2	SUB2	W only	0*	PCU9655 does not respond to I^2C-bus subaddress 2.
			1	PCU9655 responds to I^2C-bus subaddress 2.
1	SUB3	W only	0*	PCU9655 does not respond to I^2C-bus subaddress 3.
			1	PCU9655 responds to I^2C-bus subaddress 3.
0	ALLCALL	W only	0	PCU9655 does not respond to LED All Call I^2C-bus address.
			1*	PCU9655 responds to LED All Call I^2C-bus address.

[1] It takes 500 µs max. for the oscillator to be up and running once SLEEP bit has been set to logic 0. Timings on LEDn outputs are not guaranteed if PWMx, GRPPWM or GRPFREQ registers are accessed within the 500 µs window.

[2] No blinking or dimming is possible when the oscillator is off.

7.3.2 MODE2 — Mode register 2

Table 6. MODE2 - Mode register 2 (address 01h) bit description

*Legend: * default value.*

Bit	Symbol	Access	Value	Description
7	-	-	-	not used
6	-	-	-	not used
5	DMBLNK	W only	0*	group control = dimming
			1	group control = blinking
4	-	-	0*	reserved
3	OCH	W only	0*	outputs change on STOP command[1]
			1	outputs change on ninth clock cycle (USCL)
2	-	-	1*	reserved
1	-	-	0*	reserved
0	-	-	1*	reserved

[1] Change of the outputs at the STOP command allows synchronizing outputs of more than one PCU9655. Applicable to registers from 02h (LEDOUT0) to 3Ah (OFFSET) only.

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7.3.3 LEDOUT0 to LEDOUT3, LED driver output state

Table 7. LEDOUT0 to LEDOUT3 - LED driver output state registers (address 02h to 05h) bit description

*Legend: * default value.*

Address	Register	Bit	Symbol	Access	Value	Description
02h	LEDOUT0	7:6	LDR3	W only	00*	LED3 output state control
		5:4	LDR2	W only	00*	LED2 output state control
		3:2	LDR1	W only	00*	LED1 output state control
		1:0	LDR0	W only	00*	LED0 output state control
03h	LEDOUT1	7:6	LDR7	W only	00*	LED7 output state control
		5:4	LDR6	W only	00*	LED6 output state control
		3:2	LDR5	W only	00*	LED5 output state control
		1:0	LDR4	W only	00*	LED4 output state control
04h	LEDOUT2	7:6	LDR11	W only	00*	LED11 output state control
		5:4	LDR10	W only	00*	LED10 output state control
		3:2	LDR9	W only	00*	LED9 output state control
		1:0	LDR8	W only	00*	LED8 output state control
05h	LEDOUT3	7:6	LDR15	W only	00*	LED15 output state control
		5:4	LDR14	W only	00*	LED14 output state control
		3:2	LDR13	W only	00*	LED13 output state control
		1:0	LDR12	W only	00*	LED12 output state control

LDRx = 00 — LED driver x is off (default power-up state).

LDRx = 01 — LED driver x is fully on (individual brightness and group dimming/blinking not controlled).

LDRx = 10 — LED driver x individual brightness can be controlled through its PWMx register.

LDRx = 11 — LED driver x individual brightness and group dimming/blinking can be controlled through its PWMx register and the GRPPWM registers.

7.3.4 GRPPWM, group duty cycle control

Table 8. GRPPWM - Group brightness control register (address 08h) bit description

*Legend: * default value*

Address	Register	Bit	Symbol	Access	Value	Description
08h	GRPPWM	7:0	GDC[7:0]	W only	1111 1111*	GRPPWM register

When DMBLNK bit (MODE2 register) is programmed with logic 0, a 122 Hz fixed frequency signal is superimposed with the 31.25 kHz individual brightness control signal. GRPPWM is then used as a global brightness control allowing the LED outputs to be dimmed with the same value. The value in GRPFREQ is then a ‘Don’t care’.

General brightness for the 16 outputs is controlled through 256 linear steps from 00h (0 % duty cycle = LED output off) to FFh (99.6 % duty cycle = maximum brightness). Applicable to LED outputs programmed with LDRx = 11 (LEDOUT0 to LEDOUT3 registers).

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When DMBLNK bit is programmed with logic 1, GRPPWM and GRPFREQ registers define a global blinking pattern, where GRPFREQ contains the blinking period (from 15 Hz to 16.8 s) and GRPPWM the duty cycle (ON/OFF ratio in %).

$$duty\ cycle = \frac{GDC[7:0]}{256} \quad (1)$$

7.3.5 GRPFREQ, group frequency

Table 9. GRPFREQ - Group frequency register (address 09h) bit description

*Legend: * default value.*

Address	Register	Bit	Symbol	Access	Value	Description
09h	GRPFREQ	7:0	GFRQ[7:0]	W only	0000 0000*	GRPFREQ register

GRPFREQ is used to program the global blinking period when DMBLNK bit (MODE2 register) is equal to 1. Value in this register is a ‘Don’t care’ when DMBLNK = 0. Applicable to LED outputs programmed with LDRx = 11 (LEDOUT0 to LEDOUT3 registers).

Blinking period is controlled through 256 linear steps from 00h (67 ms, frequency 15 Hz) to FFh (16.8 s).

$$global\ blinking\ period = \frac{GFRQ[7:0] + 1}{15.26}(s) \quad (2)$$

7.3.6 PWM0 to PWM15, individual brightness control

Table 10. PWM0 to PWM15 - PWM registers 0 to 15 (address 0Ah to 19h) bit description

*Legend: * default value.*

Address	Register	Bit	Symbol	Access	Value	Description
0Ah	PWM0	7:0	IDC0[7:0]	W only	0000 0000*	PWM0 Individual Duty Cycle
0Bh	PWM1	7:0	IDC1[7:0]	W only	0000 0000*	PWM1 Individual Duty Cycle
0Ch	PWM2	7:0	IDC2[7:0]	W only	0000 0000*	PWM2 Individual Duty Cycle
0Dh	PWM3	7:0	IDC3[7:0]	W only	0000 0000*	PWM3 Individual Duty Cycle
0Eh	PWM4	7:0	IDC4[7:0]	W only	0000 0000*	PWM4 Individual Duty Cycle
0Fh	PWM5	7:0	IDC5[7:0]	W only	0000 0000*	PWM5 Individual Duty Cycle
10h	PWM6	7:0	IDC6[7:0]	W only	0000 0000*	PWM6 Individual Duty Cycle
11h	PWM7	7:0	IDC7[7:0]	W only	0000 0000*	PWM7 Individual Duty Cycle
12h	PWM8	7:0	IDC8[7:0]	W only	0000 0000*	PWM8 Individual Duty Cycle
13h	PWM9	7:0	IDC9[7:0]	W only	0000 0000*	PWM9 Individual Duty Cycle
14h	PWM10	7:0	IDC10[7:0]	W only	0000 0000*	PWM10 Individual Duty Cycle
15h	PWM11	7:0	IDC11[7:0]	W only	0000 0000*	PWM11 Individual Duty Cycle
16h	PWM12	7:0	IDC12[7:0]	W only	0000 0000*	PWM12 Individual Duty Cycle
17h	PWM13	7:0	IDC13[7:0]	W only	0000 0000*	PWM13 Individual Duty Cycle
18h	PWM14	7:0	IDC14[7:0]	W only	0000 0000*	PWM14 Individual Duty Cycle
19h	PWM15	7:0	IDC15[7:0]	W only	0000 0000*	PWM15 Individual Duty Cycle

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A 31.25 kHz fixed frequency signal is used for each output. Duty cycle is controlled through 256 linear steps from 00h (0 % duty cycle = LED output off) to FFh (99.6 % duty cycle = LED output at maximum brightness). Applicable to LED outputs programmed with LDRx = 10 or 11 (LEDOUT0 to LEDOUT3 registers).

$$duty\ cycle = \frac{IDCx[7:0]}{256} \quad (3)$$

7.3.7 OFFSET — LEDn output delay offset register

Table 11. OFFSET - LEDn output delay offset register (address 3Ah) bit description

*Legend: * default value.*

Address	Register	Bit	Access	Value	Description
3Ah	OFFSET	7:4	-	0000h*	not used
		3:0	W only	1000h*	LEDn output delay offset factor

The PCU9655 can be programmed to have turn-on delay between LED outputs. This helps to reduce peak current for the V_{DD} supply and reduces EMI.

The order in which the LED outputs are enabled will always be the same (channel 0 will enable first and channel 15 will enable last).

OFFSET control register bits [3:0] determine the delay used between the turn-on times as follows:

0000 = no delay between outputs (all on, all off at the same time)

0001 = delay of 1 clock cycle (125 ns) between successive outputs

0010 = delay of 2 clock cycles (250 ns) between successive outputs

0011 = delay of 3 clock cycles (375 ns) between successive outputs

:

1111 = delay of 15 clock cycles (1.875 μs) between successive outputs

Example: If the value in the OFFSET register is 1000 the corresponding delay = 8 × 125 ns = 1 μs delay between successive outputs.

channel 0 turns on at time 0 μs

channel 1 turns on at time 1 μs

channel 2 turns on at time 2 μs

channel 3 turns on at time 3 μs

channel 4 turns on at time 4 μs

channel 5 turns on at time 5 μs

channel 6 turns on at time 6 μs

channel 7 turns on at time 7 μs

channel 8 turns on at time 8 μs

channel 9 turns on at time 9 μs

channel 10 turns on at time 10 μs

channel 11 turns on at time 11 μs

channel 12 turns on at time 12 μs

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channel 13 turns on at time 13 μs

channel 14 turns on at time 14 μs

channel 15 turns on at time 15 μs

7.3.8 SUBADR[3:1] LED Sub Call UFm I²C-bus addresses for PCU9655

Table 12. SUBADR1 to SUBADR3 - I²C-bus subaddress registers 1 to 3 (address 3Bh to 3Dh) bit description

*Legend: * default value.*

Address	Register	Bit	Symbol	Access	Value	Description
3Bh	SUBADR1	7:1	A1[7:1]	W only	1010 110*	I²C-bus subaddress 1
		0	A1[0]	W only	0*	reserved
3Ch	SUBADR2	7:1	A2[7:1]	W only	1010 110*	I²C-bus subaddress 2
		0	A2[0]	W only	0*	reserved
3Dh	SUBADR3	7:1	A3[7:1]	W only	1010 110*	I²C-bus subaddress 3
		0	A3[0]	W only	0*	reserved

Default power-up values are ACh, ACh, ACh. At power-up, SUBADR1 is enabled while SUBADR2 and SUBADR3 are disabled. The power-up default bit subaddress of ACh indicates that this device is a 16-channel LED driver.

All three subaddresses are programmable. Once subaddresses have been programmed to their right values, SUBx bits in MODE1 register (00h) need to be set to logic 1 in order to have the device respond to these addresses. When SUBx is set to logic 1, the corresponding I²C-bus subaddress can be used during an UFm I²C-bus write sequence.

7.3.9 ALLCALLADR, LED All Call I²C-bus address

Table 13. ALLCALLADR - LED All Call I²C-bus address register (address 3Eh) bit description

*Legend: * default value.*

Address	Register	Bit	Symbol	Access	Value	Description
3Eh	ALLCALLADR	7:1	AC[7:1]	W only	1010 000*	ALLCALL I²C-bus address register
		0	AC[0]	W only	0*	reserved

The LED All Call I²C-bus address allows all the PCU9655s on the bus to be programmed at the same time (ALLCALL bit in register MODE1 must be equal to logic 1 (power-up default state)). This address is programmable through the I²C-bus and can be used during an I²C-bus write sequence. The register address can also be programmed as a Sub Call.

Only the 7 MSBs representing the All Call I²C-bus address are valid. The LSB in the ALLCALLADR register is a 0.

7.3.10 RESERVED1

This register is reserved.

7.3.11 RESERVED2, RESERVED3

These registers are reserved.

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7.3.12 PWMALL — brightness control for all LEDn outputs

When programmed, the value in this register will be used for PWM duty cycle for all the LEDn outputs.

Table 14. PWMALL - brightness control for all LEDn outputs register (address 42h) bit description

*Legend: * default value.*

Address	Register	Bit	Access	Value	Description
42h	PWMALL	7:0	W only	0000 0000h*	duty cycle for all LEDn outputs

Remark: Write to any of the PWM0 to PWM15 registers will overwrite the value in corresponding PWMn register.

7.3.13 Overtemperature protection

If the PCU9655 chip temperature exceeds its limit ($T_{th(otp)}$, see Table 17), all output channels will be disabled until the temperature drops below its limit minus a small hysteresis (T_{hys}, see Table 17). Once the die temperature reduces below the $T_{th(otp)} - T_{hys}$, the chip will return to the same condition it was prior to the overtemperature event.

7.4 Power-on reset

When power is applied to V_{DD}, an internal power-on reset holds the PCU9655 in a reset condition until V_{DD} has reached V_{POR}. At this point, the reset condition is released and the PCU9655 registers and I^2C-bus state machine are initialized to their default states (all zeroes) causing all the channels to be deselected. Thereafter, V_{DD} must be pulled lower than 1 V and stay LOW for longer than 20 μs. The device will reset itself, and allow 2 ms for the device to fully wake up.

7.5 Hardware reset recovery

When a reset of PCU9655 is activated using an active LOW input on the $\overline{\text{RESET}}$ pin, a reset pulse width of 2.5 μs minimum is required. The maximum wait time after $\overline{\text{RESET}}$ pin is released is 2 ms.

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7.6 Software reset

The Software Reset Call (SWRST Call) allows all the devices in the UFm I^2C-bus to be reset to the power-up state value through a specific formatted I^2C-bus command.

The maximum wait time after software reset is 1 ms.

The SWRST Call function is defined as the following:

1. A START command is sent by the UFm I^2C-bus master.
2. The reserved General Call address '0000 000' with the $\overline{W}$ bit set to '0' (write) is sent by the UFm I^2C-bus master.
3. Since PCU9655 is a UFm I^2C-bus device, no acknowledge is returned to the I^2C-bus master.
4. Once the General Call address has been sent, the master sends 1 byte with 1 specific value (SWRST data byte 1): Byte 1 = 06h.

   If more than 1 byte of data is sent, they will be ignored by the PCU9655.
5. Once the correct byte (SWRST data byte 1) has been sent, the master sends a STOP command to end the SWRST function: the PCU9655 then resets to the default value (power-up value) and is ready to be addressed again within the specified bus free time (t_{BUF}).

Remark: The reset stage is also the standby state with the internal oscillator turned off. It takes 500 μs for the oscillator to be up and running once the SLEEP bit has been set to a logic 1. PWM registers should not be accessed within the 500 μs window.

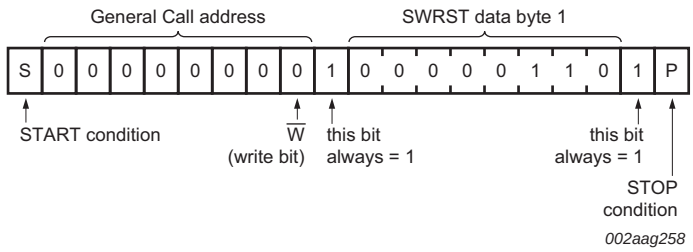


Fig 5. SWRST Call

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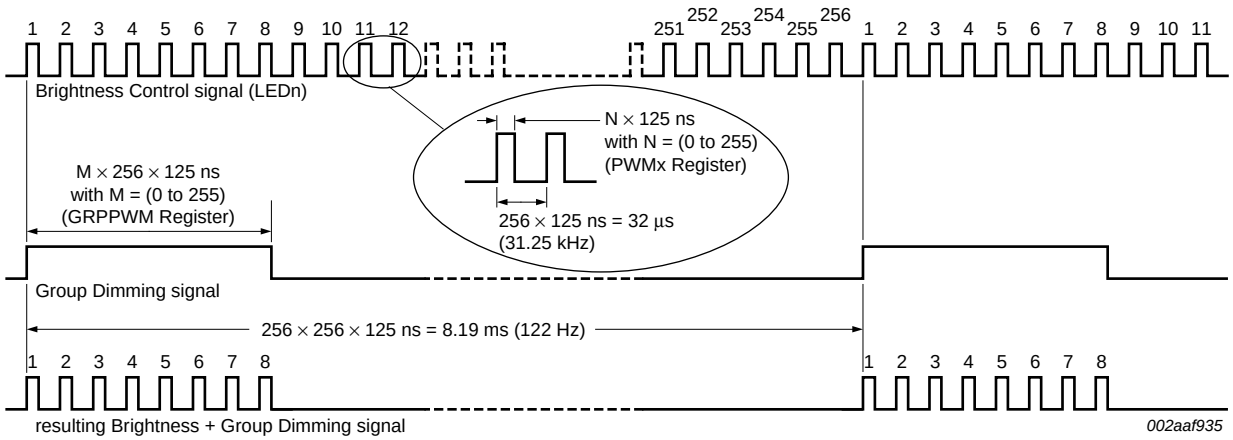
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7.7 Individual brightness control with group dimming/blinking

A 31.25 kHz fixed frequency signal with programmable duty cycle (8 bits, 256 steps) is used to control individually the brightness for each LED.

On top of this signal, one of the following signals can be superimposed (this signal can be applied to the 16 LED outputs LED0 to LED15 because the count started at 0):

- A lower 122 Hz fixed frequency signal with programmable duty cycle (8 bits, 256 steps) is used to provide a global brightness control.
- A programmable frequency signal from 15 Hz to every 16.8 seconds (8 bits, 256 steps) with programmable duty cycle (8 bits, 256 steps) is used to provide a global blinking control.



Minimum pulse width for LEDn Brightness Control is 125 ns.

Minimum pulse width for Group Dimming is 32 µs.

When M = 1 (GRPPWM register value), the resulting LEDn Brightness Control + Group Dimming signal will have 1 pulse of the LED Brightness Control signal (pulse width = N × 125 ns, with 'N' defined in PWMx register).

This resulting Brightness + Group Dimming signal above shows a resulting Control signal with M = 8.

Fig 6. Brightness + Group Dimming signals

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8. Characteristics of the PCU9655 Ultra Fast-mode I²C-bus

The PCU9655 LED controller uses the new Ultra Fast-mode (UFm) I²C-bus to communicate with the UFm I²C-bus capable host controller. Like the Standard mode and Fast-mode Plus (Fm+) I²C-bus, it uses two lines for communication. They are a serial data line (USDA) and a serial clock line (USCL). The UFm is a unidirectional bus that is capable of higher frequency (up to 5 MHz). The UFm I²C-bus slave devices operate in receive-only mode. That is, only I²C writes to PCU9655 are supported.

8.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the USDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see Figure 7).

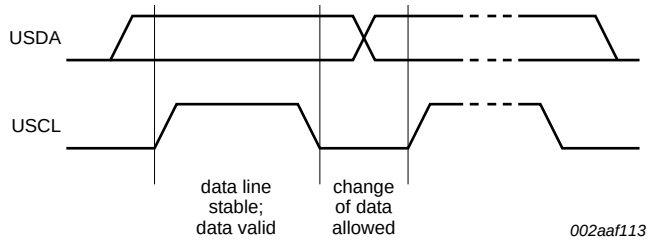


Fig 7. Bit transfer

8.1.1 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P) (see Figure 8).

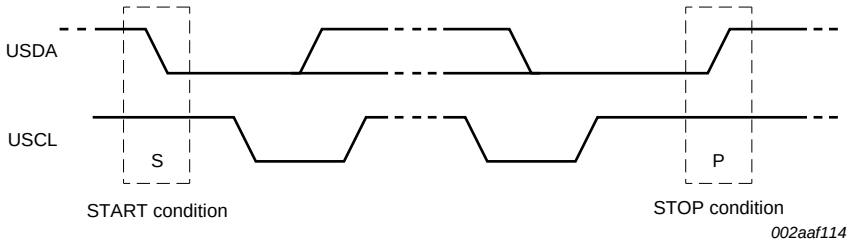


Fig 8. Definition of START and STOP conditions

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8.2 System configuration

A device generating a message is a ‘transmitter’; a device receiving is the ‘receiver’. The device that controls the message is the ‘master’ and the devices which are controlled by the master are the ‘slaves’ (see Figure 9).

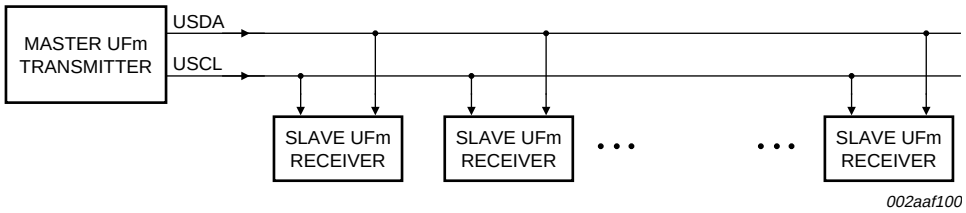


Fig 9. System configuration

8.3 Data transfer

The number of data bytes transferred between the START and the STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one bit that is always set to 1. The master generates an extra related clock pulse.

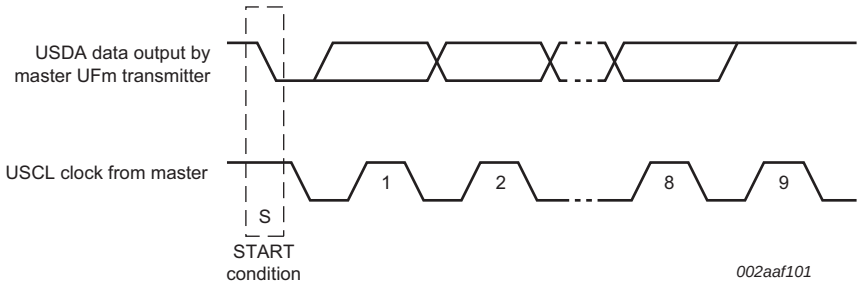
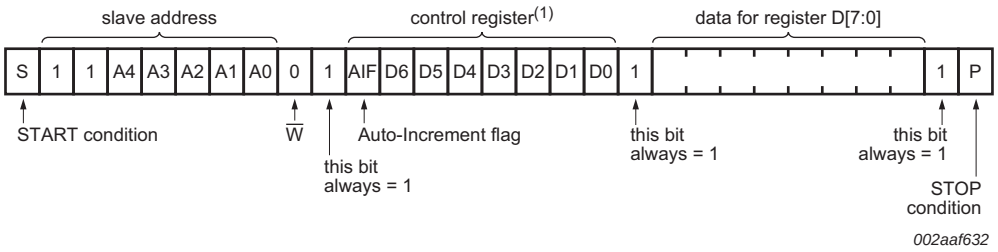


Fig 10. Data transfer

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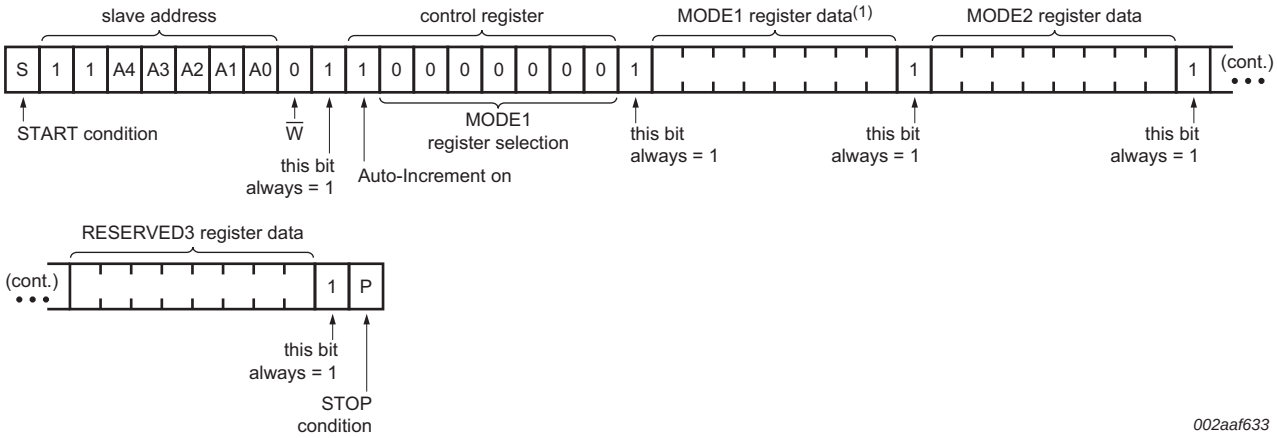
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9. Bus transactions



(1) See Table 4 for register definition.

Fig 11. Write to a specific register



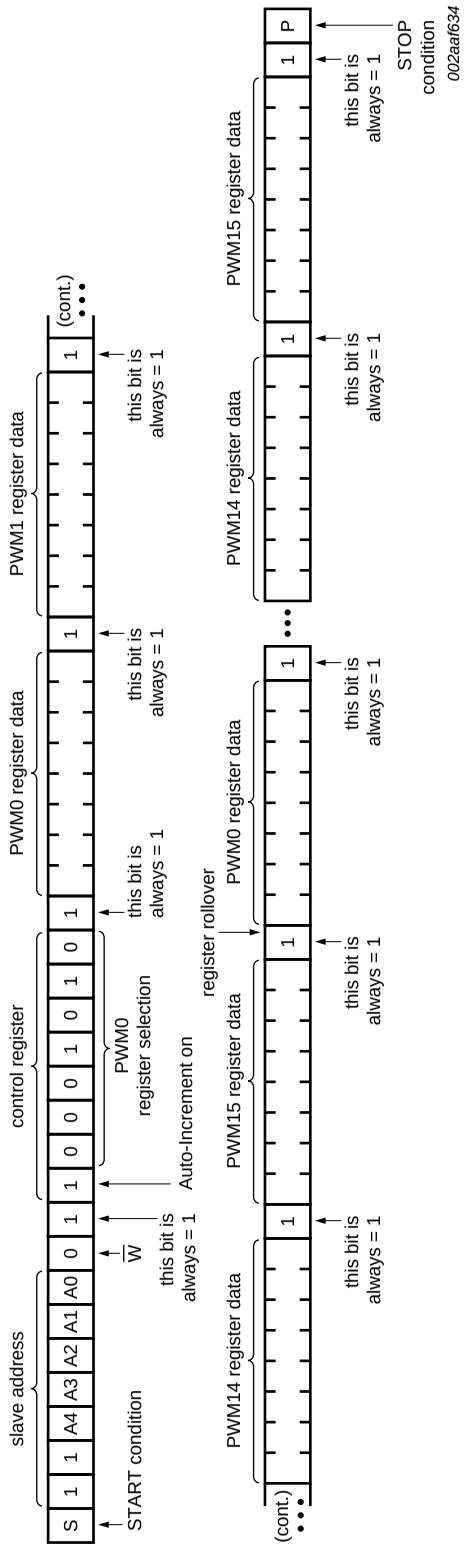
(1) AI1, AI0 = 00. See Table 3 for Auto-Increment options.

Remark: Care should be taken to load the appropriate value here in the AI1 and AI0 bits of the MODE1 register for programming the part with the required Auto-Increment options.

Fig 12. Write to all registers using the Auto-Increment feature

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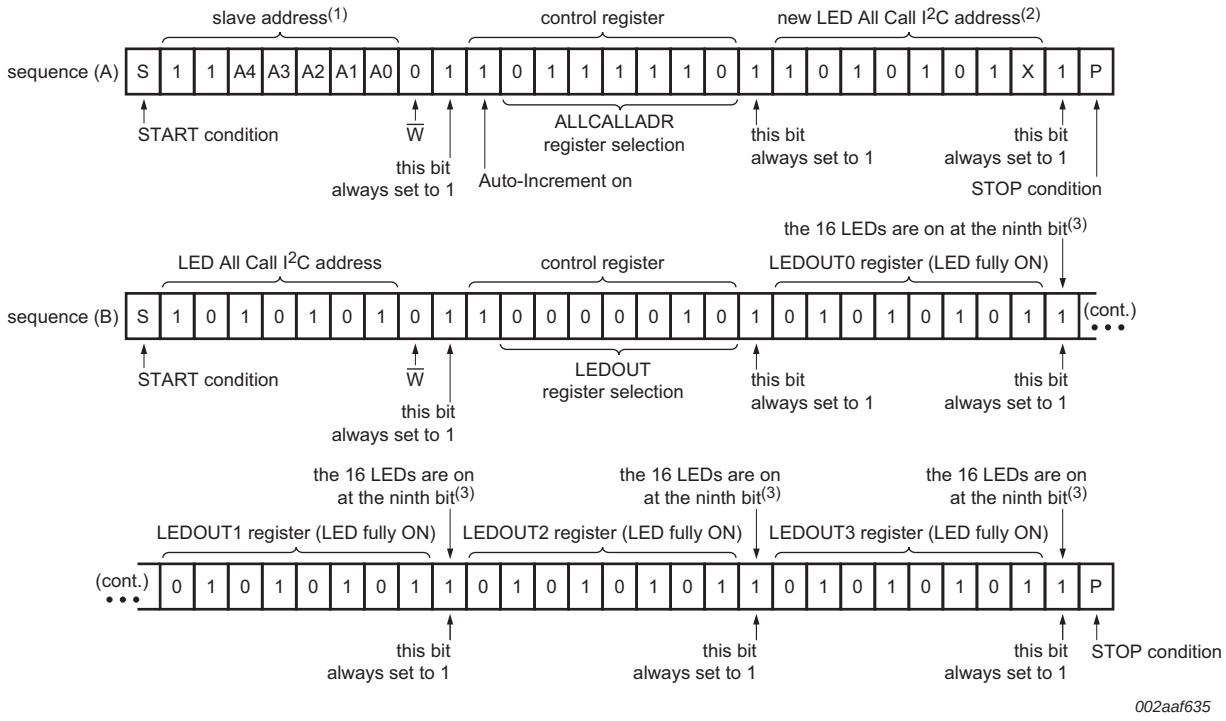


This example assumes that AIF + AI[1:0] = 101b.

Fig 13. Multiple writes to Individual Brightness registers only using the Auto-Increment feature

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(1) In this example, several PCU9655s are used and the same sequence (A) (above) is sent to each of them.

(2) ALLCALL bit in MODE1 register is previously set to 1 for this example.

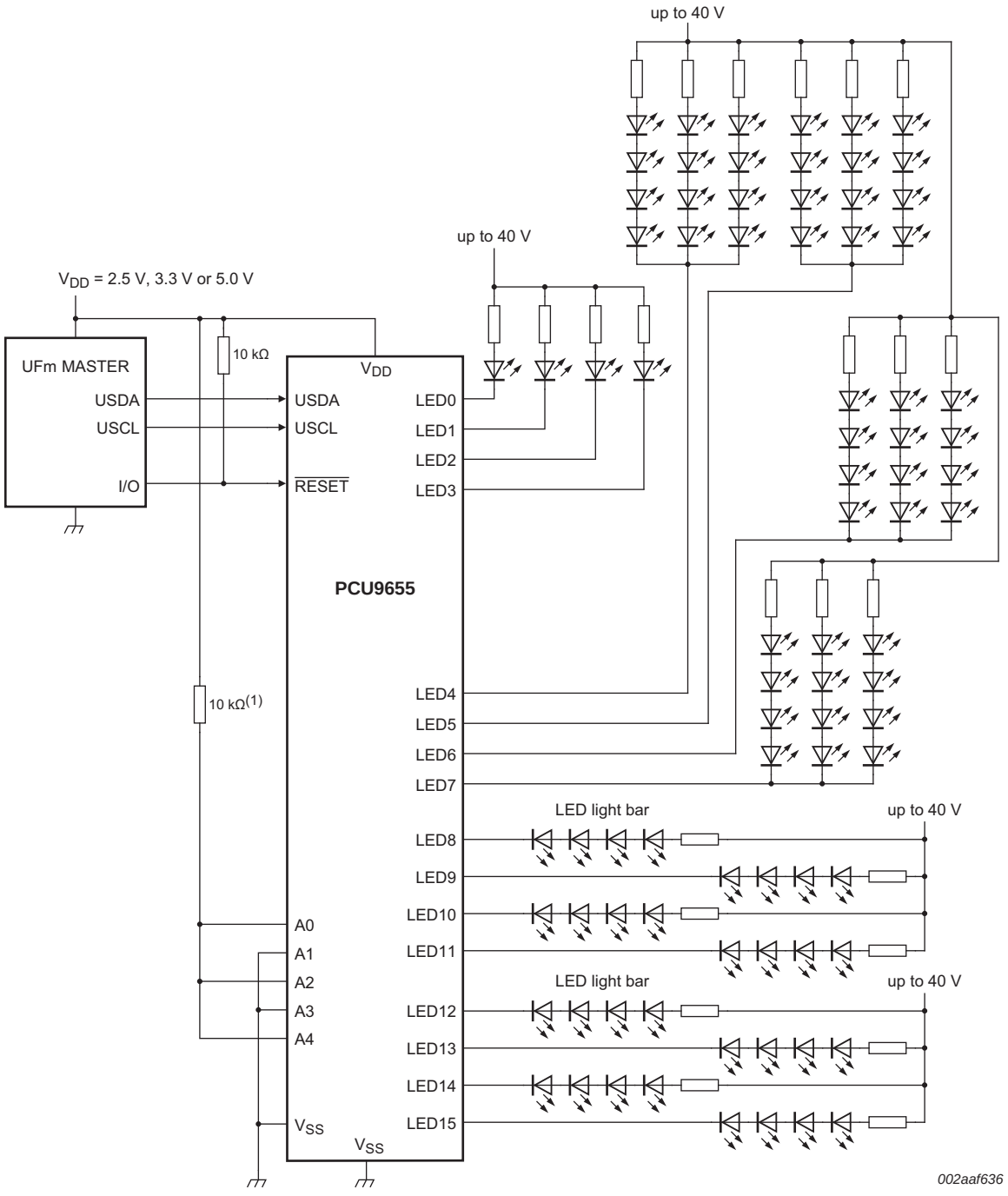
(3) OCH bit in MODE2 register is previously set to 1 for this example.

Fig 14. LED All Call I²C-bus address programming and LED All Call sequence example

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10. Application design-in information



(1) A standard 10 kΩ pull-up resistor is required to obtain the best system level ESD performance.

Fig 15. Typical application

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10.1 Thermal considerations

Since the PCU9655 device integrates 16 voltage switches, thermal considerations should be taken into account to prevent overheating, which can cause the device to go into thermal shutdown.

In order to ensure that the device will not go into thermal shutdown when operating under certain application conditions, its junction temperature (T_j) should be calculated to ensure that is below the overtemperature threshold limit (125 °C). The T_j of the device depends on the ambient temperature (T_{amb}), device's total power dissipation (P_{tot}), and thermal resistance.

The device junction temperature can be calculated by using the following equation:

$$T_j = T_{amb} + R_{th(j\text{-}a)} \times P_{tot} \quad (4)$$

where:

T_j = junction temperature

T_{amb} = ambient temperature

$R_{th(j\text{-}a)}$ = junction to ambient thermal resistance

P_{tot} = (device) total power dissipation

An example of this calculation is show below:

Conditions:

T_{amb} = 50 °C

$R_{th(j\text{-}a)}$ = 65 °C/W (per JEDEC 51 standard for multilayer PCB)

I_{LED} = 100 mA / channel

$I_{DD(max)}$ = 12 mA

V_{DD} = 5 V

P_{tot} calculation:

P_{tot} = IC_power + LED drivers_power;

IC_power = ($I_{DD} \times V_{DD}$)

IC_power = (0.012 A × 5 V) = 0.06 W

LED drivers_power = 16 × ($I_{LED}^2 \times R_{on}$)

LED drivers_power = 16 × ((0.1 A)^2 × 5 Ω) = 0.8 W

P_{tot} = 0.06 W + 0.8 W = 0.86 W

T_j calculation:

$T_j = T_{amb} + R_{th(j\text{-}a)} \times P_{tot}$

T_j = 50 °C + (65 °C/W × 0.86 W) = 105.9 °C

This confirms that the junction temperature is below the minimum overtemperature threshold of 125 °C, which ensures the device will not go into thermal shutdown under these conditions.

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It is important to mention that the value of the thermal resistance junction-to-ambient ($R_{th(j-a)}$) strongly depends on the PCB design. Therefore, the device pins should be attached to a big enough PCB copper area to ensure proper thermal dissipation (similar to JEDEC 51 standard). Several thermal vias should be used as well in a multi-layer PCB design to increase the effectiveness of the heat dissipation.

Finally it is important to point out that this calculation should be taken as a reference only and therefore evaluations should still be performed under the application environment and conditions to confirm proper system operation.

11. Limiting values

Table 15. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage			–0.5	+6.0	V
$V_{I/O}$	voltage on an input/output pin			V_{SS} – 0.5	5.5	V
$V_{drv(LED)}$	LED driver voltage			V_{SS} – 0.5	40	V
$I_{O(LEDn)}$	output current on pin LEDn			-	105	mA
I_{SS}	ground supply current	per V_{SS} pin		-	1.0	A
I_{lu}	latch-up current	JESD	[1]	-	90	mA
P_{tot}	total power dissipation	T_{amb} = 25 °C		-	1.54	W
		T_{amb} = 85 °C		-	0.61	W
T_{stg}	storage temperature			–65	+150	°C
T_{amb}	ambient temperature	operating		–40	+85	°C
T_j	junction temperature			–40	+125	°C

[1] Class II, Level B for A2, A3. All other pins are Class II, Level A (±100 mA).

12. Thermal characteristics

Table 16. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	TSSOP28	[1]	65	°C/W

[1] Per JEDEC 51 standard for multilayer PCB.

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13. Static characteristics

Table 17. Static characteristics

V_{DD} = 3 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supply							
V_{DD}	supply voltage			3	-	5.5	V
I_{DD}	supply current	on pin V_{DD}; operating mode; no load; f_{USCL} = 5 MHz					
		V_{DD} = 3.3 V		-	6.5	16	mA
		V_{DD} = 5.5 V		-	7.0	16	mA
I_{stb}	standby current	on pin V_{DD}; no load; f_{USCL} = 0 Hz; MODE1[4] = 1; $V_I = V_{DD}$					
		V_{DD} = 3.3 V		-	550	950	µA
		V_{DD} = 5.5 V		-	550	950	µA
V_{POR}	power-on reset voltage	no load; $V_I = V_{DD}$ or V_{SS}		-	2.65	2.8	V
V_{PDR}	power-down reset voltage	no load; $V_I = V_{DD}$ or V_{SS}	[1]	0.8	1.25	-	V
Input USCL; input USDA							
V_{IL}	LOW-level input voltage			−0.5	-	$+0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	5.5	V
I_L	leakage current	$V_I = V_{DD}$ or V_{SS}		−1	-	+1	µA
C_i	input capacitance	$V_I = V_{SS}$		-	6	10	pF
LED driver outputs (LED[15:0])							
$V_{drv(LED)}$	LED driver voltage			0	-	40	V
$I_{L(off)}$	off-state leakage current	V_O = 40 V		−1	-	+1	µA
R_{on}	ON-state resistance	I_O = 100 mA; V_{DD} = 3 V		-	2	5.0	Ω
V_{trip}	trip voltage		[2][3]	-	$^2/_3V_{DD}$	-	V
I_{Olim}	output current limit	V_O = 3 V; V_{DD} = 5 V		-	0.4	0.6	A
C_o	output capacitance			-	2.5	5	pF
Address inputs, $\overline{\text{RESET}}$ input							
V_{IL}	LOW-level input voltage			−0.5	-	$+0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	5.5	V
I_{LI}	input leakage current			−1	-	+1	µA
C_i	input capacitance			-	3.7	5	pF
Overtemperature protection							
$T_{th(otp)}$	overtemperature protection threshold temperature	rising		125	-	150	°C
T_{hys}	hysteresis temperature			-	20	-	°C

[1] V_{DD} must be lowered to 0.8 V in order to reset part.

[2] Maximum on-state voltage across the switch.

[3] If the LEDn output is set to 100 % duty cycle during the shorted condition ($V_{LED} > {}^2/_3V_{DD}$), the output will be latched off until the next POR. If the LEDn output is duty cycling (PWM duty cycle < 100 %), the output will turn off 300 ns after it is turned on during the shorted condition ($V_{LED} > {}^2/_3V_{DD}$).

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14. Dynamic characteristics

Table 18. Dynamic characteristics

All the timing limits are valid within the operating supply voltage and ambient temperature range; V_{DD} = 3 V ± 0.2 V and 5.5 V ± 0.3 V; T_{amb} = −40 °C to +85 °C; and refer to V_{IL} and V_{IH} with an input voltage of V_{SS} to V_{DD}.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
f_{USCL}	USCL clock frequency		[1]	0	-	5	MHz
t_{BUF}	bus free time between a STOP and START condition			0.08	-	-	µs
$t_{HD;STA}$	hold time (repeated) START condition			0.05	-	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition			0.05	-	-	µs
$t_{SU;STO}$	set-up time for STOP condition			0.05	-	-	µs
$t_{HD;DAT}$	data hold time			10	-	-	ns
$t_{SU;DAT}$	data set-up time			30	-	-	ns
t_{LOW}	LOW period of the USCL clock			50	-	-	ns
t_{HIGH}	HIGH period of the USCL clock			50		-	ns
t_f	fall time of both USDA and USCL signals			-		50	ns
t_r	rise time of both USDA and USCL signals			-		50	ns
t_{SP}	pulse width of spikes that must be suppressed by the input filter			-		10	ns
Output port timing	[2][3]						
$t_{d(USCL-Q)}$	delay time from USCL to data output	USCL to LEDn; MODE2[3] = 1; LEDOUTx = 01; outputs change on ninth clock cycle (USCL)		-	-	450	ns
$t_{d(USDA-Q)}$	delay time from USDA to data output	USDA to LEDn; MODE2[3] = 0; LEDOUTx = 01; outputs change on STOP condition		-	-	450	ns

[1] Minimum USCL clock frequency is limited by the bus time-out feature, which resets the serial bus interface if either USDA or USCL is held LOW for a minimum of 25 ms. Disable bus time-out feature for DC operation.

[2] From LED off to fully on, LED fully on to off, or LED individual brightness control to off.

[3] For LED off state to on with individual brightness control or for changes in the individual brightness control value, there is a synchronization that may take up to 15 µs for the change to take effect.

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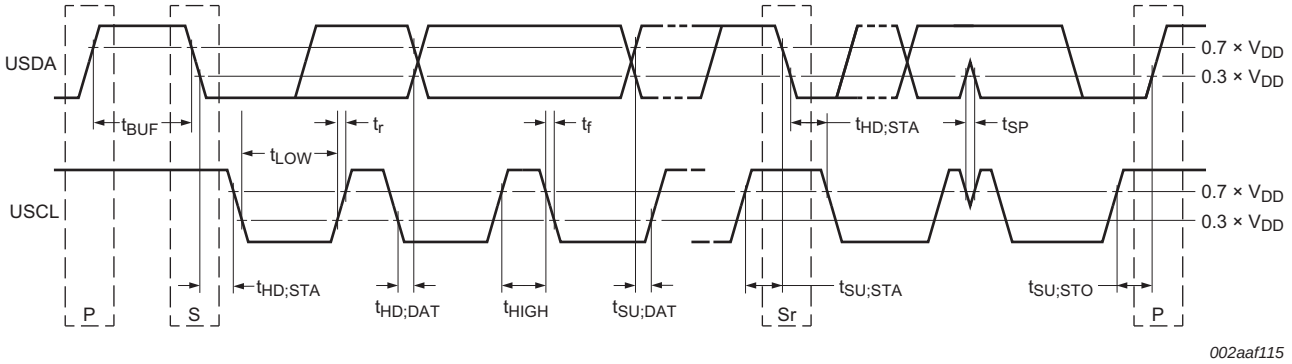
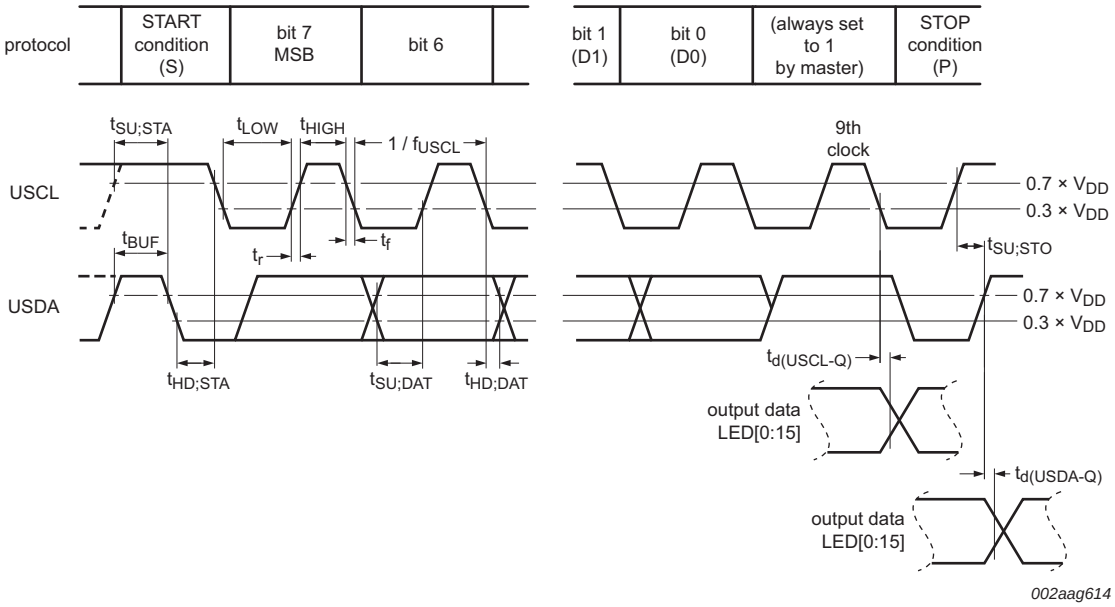


Fig 16. Definition of timing



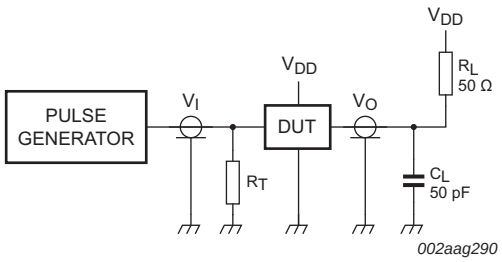
Rise and fall times refer to V_{IL} and V_{IH}.

Fig 17. UFm I²C-bus timing diagram

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15. Test information



R_L = Load resistor for LEDn.

C_L = Load capacitance includes jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generators.

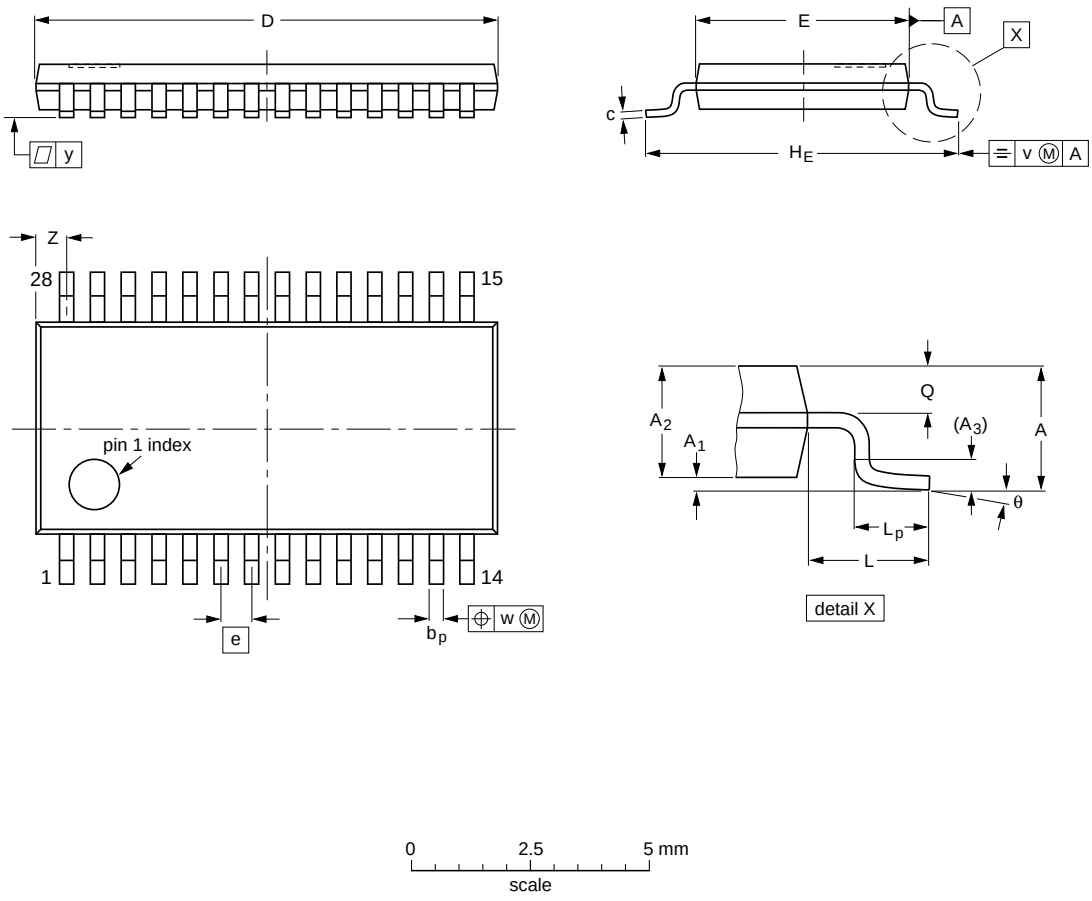
Fig 18. Test circuitry for switching times

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16. Package outline

TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm **SOT361-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	9.8 9.6	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.8 0.5	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT361-1		MO-153				~~99-12-27~~ 03-02-19

Fig 19. Package outline SOT361-1 (TSSOP28)

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17. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

18. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

18.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

18.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

18.3 Wave soldering

Key characteristics in wave soldering are:

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- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

18.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 20) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 19 and 20

Table 19. SnPb eutectic process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm^3)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 20. Lead-free process (from J-STD-020C)

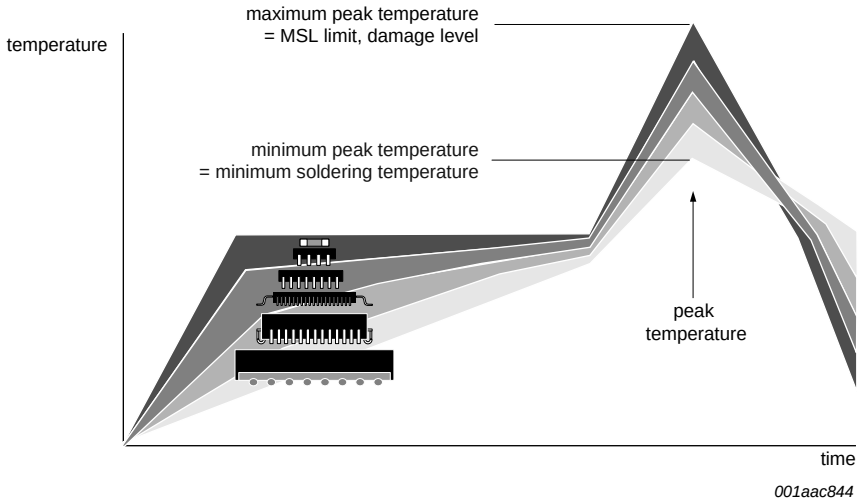
Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm^3)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 20.

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MSL: Moisture Sensitivity Level

Fig 20. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

19. Abbreviations

Table 21. Abbreviations

Acronym	Description
CDM	Charged-Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
FET	Field-Effect Transistor
HBM	Human Body Model
I^2C-bus	Inter-Integrated Circuit bus
LED	Light Emitting Diode
LCD	Liquid Crystal Display
LSB	Least Significant Bit
MSB	Most Significant Bit
NMOS	Negative-channel Metal-Oxide Semiconductor
PCB	Printed-Circuit Board
PMOS	Positive-channel Metal-Oxide Semiconductor
PWM	Pulse Width Modulation
RGB	Red/Green/Blue
RGBA	Red/Green/Blue/Amber
SMBus	System Management Bus
UFm	Ultra Fast mode

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20. References

[1] **AN10897, “A guide to designing for ESD and EMC” —** NXP Semiconductors

[2] **AN11131, “How to improve system level ESD performance” —** NXP Semiconductors

21. Revision history

Table 22. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCU9655 v.2	20121002	Product data sheet	-	PCU9655 v.1
Modifications:	• Figure 2b: sub-title corrected from “PCU9665PW1” to “PCU9655PW1” • Section 7.2 “Control register”, second paragraph on page 8: changed from “AI0 = 1” to “AI0 = 0” • Table 5 “MODE1 - Mode register 1 (address 00h) bit description”, Table note [1]: changed from “set to logic 1” to “set to logic 0” • Section 7.5 “Hardware reset recovery”: first paragraph, second sentence: deleted “(typical)” • Section 7.6 “Software reset”: second paragraph, first sentence: deleted “(typical)” • Table 18 “Dynamic characteristics”: added sub-section “Output port timing” • Figure 17 “UFm I^2C-bus timing diagram” updated (added $t_{d(USCL-Q)}$ and $t_{d(USDA-Q)}$ timing)			
PCU9655 v.1	20111117	Product data sheet	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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